

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6800649

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ROBERT J. STACEY	04/08/2020
CARLOS CORDEIRO	04/08/2020
CHITTABRATA GHOSH	12/28/2020
DANIEL F. BRAVO	04/10/2020
DIBAKAR DAS	06/30/2021
LAURENT CARIOU	05/26/2021
PO-KAI HUANG	04/08/2020
XIAOGANG CHEN	06/16/2021
ARIK KLEIN	04/12/2020
DANNY ALEXANDER	04/13/2020
CHENG CHEN	04/08/2020
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BLVD.
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17329763
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	612-373-6900
Email:	request@slwip.com
Correspondent Name:	SCHWEGMAN, LUNDBERG & WOESSNER/INTEL
Address Line 1:	PO BOX 2938
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402

ATTORNEY DOCKET NUMBER:	1884.A20US2
NAME OF SUBMITTER:	NANCY CUNDALL
SIGNATURE:	/Nancy Cundall/
DATE SIGNED:	07/07/2021

Total Attachments: 34

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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Robert J. Stacey, Carlos Cordeiro, Chittabrata Ghosh, Daniel F. Bravo, Dibakar Das, Laurent Cariou, Po-Kai Huang, Xiaogang Chen, Arik Klein, Danny Alexander, Cheng Chen>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

MULTI-LINK DISCOVERY SIGNALING IN EXTREMELY HIGH THROUGHPUT (EHT) SYSTEMS

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on March 20, 2020 as

United States of America Application Number 16/825,028

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

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/rjstacey/

Robert J. Stacey

4/8/2020

Date Signed

Carlos Cordeiro

Date Signed

Chittabrata Ghosh

Date Signed

Daniel F. Bravo

Date Signed

Dibakar Das

Date Signed

Laurent Cariou

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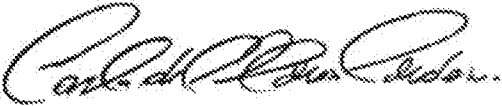
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Robert J. Stacey

Carlos Cordeiro

Date Signed

April 08, 2020
Date Signed

Chittabrata Ghosh

Date Signed

Daniel F. Bravo

Date Signed

Dibakar Das

Date Signed

Laurent Cariou

Date Signed

Po-Kai Huang

Date Signed

Xiaogang Chen

Date Signed

Arik Klein

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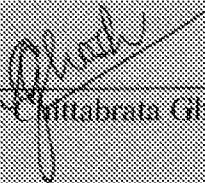
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Robert J. Stacey

Date Signed

Carlos Cordeiro

Date Signed



Chittabrata Ghosh

12/28/2020
Date Signed

Daniel F. Bravo

Date Signed

Dibakar Das

Date Signed

Laurent Cariou

Date Signed

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Robert J. Stacey

Date Signed

Carlos Cordeiro

Date Signed

Chittabrata Ghosh

Date Signed



Daniel F. Bravo

4-10-2020

Date Signed

Dibakar Das

Date Signed

Laurent Cariou

Date Signed

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Intel Docket No.: AC8581 US
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1884.A20US1

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Dibakar Das

06/30/21

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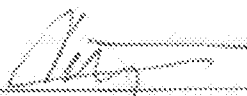
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05-26-2021
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Chittabrata Ghosh	Date Signed
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Laurent Cariou	Date Signed
	04/08/2020
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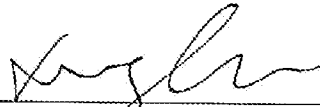
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all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Robert J. Stacey	Date Signed
Carlos Cordeiro	Date Signed
Chittabrata Ghosh	Date Signed
Daniel F. Bravo	Date Signed
Dibakar Das	Date Signed
Laurent Cariou	Date Signed
Po-Kai Huang	Date Signed

Intel Docket No.: AC8581-US
SLW Reference No.: (AC8581-US)
1884.A20US1



Xieogang Chen

6/16/21

Date Signed

Arik Klein

Date Signed

Danny Alexander

Date Signed

Cheng Chen

Date Signed

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Robert J. Stacey, Carlos Cordeiro, Chittabrata Ghosh, Daniel F. Bravo, Dibakar Das, Laurent Cariou, Po-Kai Huang, Xiaogang Chen, Arik Klein, Danny Alexander, Cheng Chen>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

MULTI-LINK DISCOVERY SIGNALING IN EXTREMELY HIGH THROUGHPUT (EHT) SYSTEMS

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on March 20, 2020 as

United States of America Application Number 16/825,028

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

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Dibakar Das	Date Signed
Laurent Cariou	Date Signed
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Xiaogang Chen



Arik Klein

Date Signed

April 12th 2020

Date Signed

Danny Alexander

Date Signed

Cheng Chen

Date Signed

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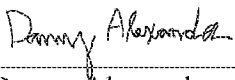
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Xiaogang Chen

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Arik Klein

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Danny Alexander

April 13th 2020

Date Signed

Cheng Chen

Date Signed

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Danny Alexander

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Cheng Chen

04/08/2020

Date Signed